IN THE CLAIMS:

1. (Currently Amended) A method of adhering large seasoning bits on a food substrate, said method comprising the steps of:

a) mixing a dry adhesive with a plurality of three-dimensional seasoning bits to form an adhesive-bit mix wherein said bits are substantially between 1.7 to 17 mm in diameter;

b) cooking a food substrate having a surface to apply said bits;

c) applying said adhesive-bit mix to said food substrate, wherein said food substrate comprises no added water;

d) heating said adhesive-bit mix to a temperature above a glass transition temperature of said dry adhesive wherein said glass transition temperature is between about 40 °C to 60 °C and further wherein said dry adhesive comprises a moisture content of about 4 to 8%; and

e) cooling said adhesive-bit mix to a temperature below the glass transition temperature of said dry adhesive such that said dry adhesive hardens and adheres said bits to said food substrate.

2. (Original) The method of claim 1 further comprising the steps of:

f) applying a second topping to said food substrate; and

g) melting said second topping on said food substrate.

3. (Currently Amended) The method of claim 1 further comprising the steps of:

f) applying a non-aqueous liquid adhesive spray to said food substrate; and

g) applying a seasoning powder to said food substrate.

4. (Original) The method of claim 1 wherein said mixing of step a) is performed in a device selected from the group consisting of a mixer, a batch tumbler, a continuous tumbler, a batch blender, a continuous blender, or a ribbon blender.

5. (Original) The method of claim 1 wherein said adhesive-bit mix in step c) is applied via a topping unit.

6. (Original) The method of claim 1 wherein said cooking of said food substrate in step b) occurs by frying in a monolayer fryer.

7. (Original) The method of claim 1 wherein said cooking of said food substrate in step b) occurs by baking.

8. (Currently Amended) The method of claim 1 wherein said adhesive-bit mix comprises:

about 30 to 85% three-dimensional bits;

about 0 to 10% temporary non-aqueous liquid adhesive; and

about 15 to 60% dry adhesive.

9. (Original) The method of claim 8 wherein said dry adhesive is selected from the group consisting of corn syrup solids, dextrose, sucrose, polydextrose, and mixtures thereof.

10. (Original) The method of claim 1 wherein said dry adhesive comprises corn syrup solids with a Dextrose Equivalent of 20 or greater.

11. (Original) The method of claim 1 wherein a multi-layered food substrate is made by repeating steps c) through e) at least once.

12. (Original) The method of claim 1 wherein said food substrate is substantially flat.

13. (Original) A food product made by the method of claim 1.

14. (Currently Amended) A packaged, topped snack food comprising, in proportions based upon the total weight of the topped chip:

about 5 to 30% by weight of a food substrate;

about 40 to 95% of an adhesive-bit mix, wherein said bits are substantially between 1.7 to 17 mm in diameter wherein said bits comprise:

about 30 to 85% three-dimensional bits;

about 0 to 10% temporary non-aqueous liquid adhesive; and

about 15 to 60% a dry adhesive wherein said adhesive provides an adhering means for adhering the bits to the chip;

about 0 to 10% cheese;

about 0 to 10% non-aqueous liquid adhesive; and

about 0 to 10% seasoning powder.

15. (Original) The snack food in claim 14 wherein said food substrate comprises a fried food substrate.

16. (Original) The snack food in claim 14 wherein said food comprises a baked food substrate.

17. (Original) The snack food in claim 14 wherein said food substrate comprises an extruded food substrate.

18. (Original) The snack food claim 14 wherein said adhesive comprises corn syrup solids with a Dextrose Equivalent of 20 or greater.

19. (Original) The snack food in claim 14 wherein said food substrate is substantially flat.

20. (Original) The snack food in claim 14 wherein said food substrate comprises a food substrate cooked in a monolayer fryer.